

AMENDMENTS

IN THE CLAIMS

1. (Currently Amended) A pretreatment method for electroless plating, comprising:
adding an inorganic filler to a polymeric material;
molding the material to obtain a polymeric mold;
irradiating an area of the mold with a laser having a wavelength of 600 nm or shorter;
charging the irradiated area of the mold by generating charged and scattered substances
on the surface of the laser irradiated area of the polymeric mold; and
immersing the mold in a an ionic noble metal aqueous solution.
2. (Previously Presented) The pretreatment method for electroless plating according to claim 1, wherein 10-50 weight % of the inorganic filler is added.
3. (Previously Presented) The pretreatment method for electroless plating according to claim 1 or 2, wherein a total energy inputted by the laser to the mold is 10-500 J/cm².
4. (Previously Presented) The pretreatment method for electroless plating according to claim 1 or 2, wherein the laser is irradiated on an area of the mold so that a fluence and the number of times of irradiation are set to obtain a charging state suitable for precipitating noble metal on the irradiated area.
5. (Previously Presented) The pretreatment method for electroless plating according to claim 1 or 2, wherein the polymeric material is selected from the group consisting of a liquid crystal polymer, polyethersulfone, polybutylene terephthalate, polycarbonate, polyphenylene ether, polyphenylene oxide, polyacetal, polyethylene terephthalate, polyamide,

ABS, polyphenylene sulfide, polyetherimide, polyetherether ketone, polysulfone, polyimide, epoxy resin and composite resins thereof.

6. (Previously Presented) The pretreatment method for electroless plating according to claim 1 or 2, wherein the polymeric material comprises two or more kinds of resins having different laser ablation threshold values.

7. (Previously Presented) The pretreatment method for electroless plating according to claim 1 or 2, wherein a palladium aqueous solution is used as the noble metal aqueous solution.

8. (Previously Presented) The pretreatment method for electroless plating according to claim 1 or 2, wherein a glass filler is used as the inorganic filler.